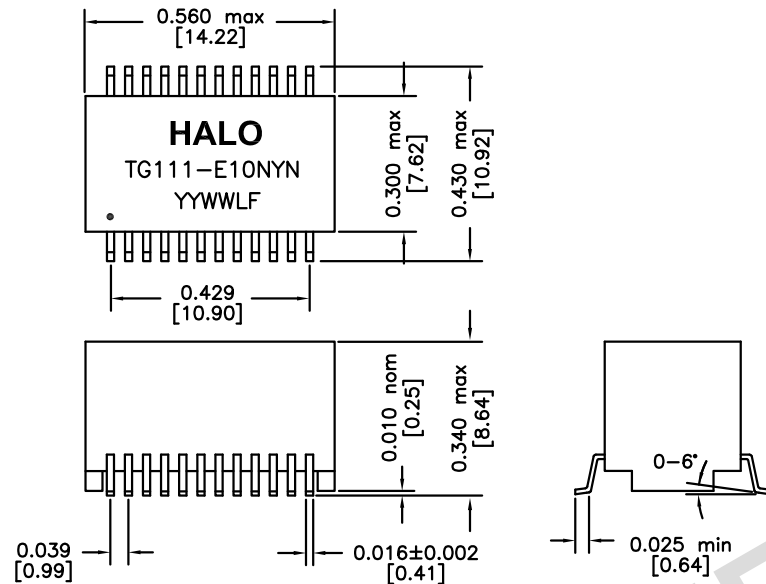
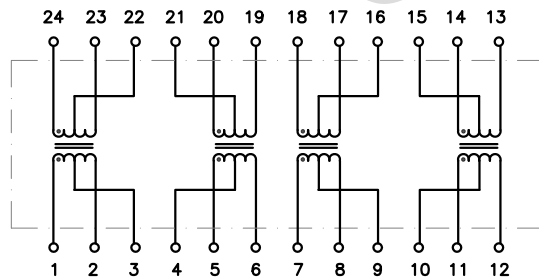




DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



PART NO. : TG111-E10NYNLF

24PIN 0.039" LEAD PITCH SMT PACKAGE

DESIGNED FOR ONE-PORT GIGABIT, IEEE802.3ab OR DUAL-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH 350mA CURRENT CARRYING CAPACITY FOR PoE

SUITABLE FOR BACK-PLANE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT, "GREEN PRODUCT"

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @ 25°C

URNS RATIO 1CT:1CT $\pm 2\%$

OCL (100KHz, 0.1Vrms, 8mADC) 350 μH min

INSERTION LOSS 1-100MHz -1.1dB max

RETURN LOSS 1-40MHz -18dB min
60MHz -14dB min
80MHz -12dB min
100MHz -10dB min

CROSSTALK 1-30MHz -50dB typ
60MHz -45dB typ
100MHz -40dB typ

ISOLATION 1,500Vrms



HALO/PBL

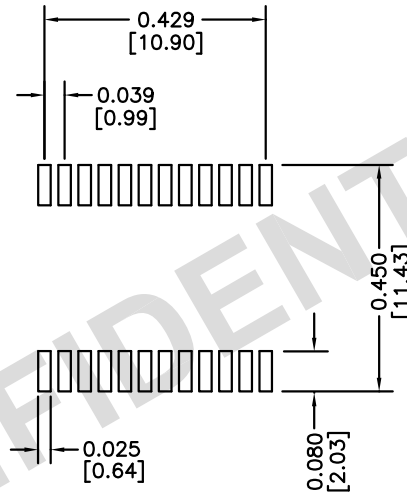
CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION MODULE
FOR FAST/GIGABIT ETHERNET
PART NO. TG111-E10NYNLF

SCALE NONE PAGE 1 OF 2

SIGNATURES	DATE	REV.	DESC.	DATE
DRAWN LI ZHI ZHONG	9/6/11	A	FIRST ISSUE	9/6/11
CHECKED LEI KEONG	5/1/13	B	PROD. RELEASE	5/1/13
APPROVED PETER LU	5/1/13			
FILE E10NYNLF.DWG				





RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

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FOR	FAST/GIGABIT ETHERNET	DRAWN LI ZHI ZHONG	9/6/11	A	FIRST ISSUE	9/6/11
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PAGE	2 OF 2	FILE E10NYNLF.DWG				